

Claims

1. An analyte sensor system, comprising
 - an analyte sensor having
 - 5 ○ a first contact pad, and
 - a second contact pad;
 - a circuit carrier having
 - a first contact area, and
 - a second contact area, wherein the second contact area comprises at least
 - 10 two individual electrically conductive surfaces; and
 - a connecting element electrically connecting the second contact pad of the analyte sensor with each of the at least two individual electrically conductive surfaces of the second contact area of the circuit carrier,
 - wherein the second contact area further comprises at least one electrically
 - 15 insulating surface between the at least two individual electrically conductive surfaces that jointly constitute the second contact area, and
 - wherein the analyte sensor comprises an electrically insulating cover which covers surfaces of the analyte sensor apart from the first contact pad and the second contact pad.
- 20 2. The analyte sensor system according to claim 1, wherein the at least two individual electrically conductive surfaces of the second contact area are electrically connected with each other outside the surface of the second contact area.
3. The analyte sensor system according to any one of the preceding claims, wherein the first contact pad is located on a first side of the analyte sensor, and wherein the
- 25 second contact pad is located on a second side of the analyte sensor.
4. The analyte sensor system according to any one of the preceding claims, wherein the first contact pad and the second contact pad are located on opposing sides of the analyte sensor.
5. The analyte sensor system according to any one of the preceding claims, wherein
- 30 the first contact pad faces the first contact area of the circuit carrier, and wherein

the second contact pad faces away from the second contact area of the circuit carrier.

6. The analyte sensor system according to any one of the preceding claims, wherein the first contact pad directly connects the first contact area of the circuit carrier.
- 5 7. The analyte sensor system according to any one of the preceding claims, wherein at least one of the first contact pad, the second contact pad, the first contact area, and the second contact area comprises a layer of an electrically conductive material.
8. The analyte sensor system according to claim 7, wherein the conductive material is
10 selected from at least one of gold or an electrically conductive carbon material.
9. The analyte sensor system according to any one of the preceding claims, wherein the connecting element comprises at least one of
 - an electrically conductive rubber;
 - an electrically conductive foam;
 - 15 – an elastomeric connector.
10. The analyte sensor system according to any one of the preceding claims, wherein the circuit carrier is or comprises a printed circuit board.
11. The analyte sensor system according to any one of the preceding claims, wherein the analyte sensor is a partially implantable analyte sensor for continuously
20 monitoring an analyte.
12. A method for producing an analyte sensor system, in particular the analyte sensor system according to any one of the preceding claims, the method comprising the steps of:
 - a) providing a circuit carrier having
 - 25 ○ a first contact area, and
 - a second contact area, wherein the second contact area comprises at least two individual electrically conductive surfaces;
 - b) arranging an analyte sensor having
 - a first contact pad, and
 - 30 ○ a second contact pad;and

- c) applying a connecting element in a manner that the connecting element electrically connects the second contact pad of the analyte sensor with each of the at least two individual electrically conductive surfaces of the second contact area of the circuit carrier.

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- 13. The method according to claim 12, wherein step b) further comprises arranging the analyte sensor in a manner that the first contact pad directly connects the first contact area of the circuit carrier.